

Supplier Name: Texas Instruments Inc. (DUNS# 00-732-1904)  
 Contact Info: [ti.com/support](http://ti.com/support)  
 Form/Declaration Type: Distribute - RoHS and IEC 62474 DB  
 Created on: 05/31/2022

Details for "LM3670MFX-ADJ/NOPB"

Current Product Information

TI part number	Lead finish/Ball material	MSL rating/peak reflow	Assembly site	Package   Pins	Package body size (mm)	Total device mass (mg)*
LM3670MFX-ADJ/NOPB	SN	Level-1-260C-UNLIM	Texas Instruments Electronics	DBV   5	2.9 x 1.6 x 1.45	18.2

\*Total Device Mass

The summary mass is a rounded value and will be within approximately +/- 10% of the detailed mass value.

Environmental Ratings Information

RoHS	REACH	Green	IEC 62474 DB
Yes	Yes	Yes	Yes

Component Information

Component	Substance	CAS Number	Amount (mg)	Homogeneous Material Level		Component Level	
				Percentage %	ppm	Percentage %	ppm
<b>Bond Wire</b>							
Copper and Its Alloys	Copper	7440-50-8	0.035651	98.734352	987344	0.195624	1956
Not Categorized	Proprietary Materials		0.000004	0.011078	111	0.000022	0
Precious Metals	Gold	7440-57-5	0.000008	0.022156	222	0.000044	0
Precious Metals	Palladium	7440-05-3	0.000444	1.229644	12296	0.002436	24
Precious Metals	Silver	7440-22-4	0.000001	0.002769	28	0.000005	0
Sub-Total			0.036108	100	1000000	0.198132	1981
<b>Die Attach Adhesive</b>							
Precious Metals	Silver	7440-22-4	0.191519	74.999902	749999	1.050904	10509
Thermoplastics	Epoxy	85954-11-6	0.06384	25.000098	250001	0.350303	3503
Sub-Total			0.255359	100	1000000	1.401208	14012
<b>Lead Frame</b>							
Copper and Its Alloys	Copper	7440-50-8	5.436408	96.509995	965100	29.830696	298307
Copper and Its Alloys	Iron	7439-89-6	0.134065	2.379993	23800	0.735642	7356
Copper and Its Alloys	Phosphorus	7723-14-0	0.00169	0.030002	300	0.009273	93
Precious Metals	Silver	7440-22-4	0.054077	0.960004	9600	0.296732	2967
Zinc and Its Alloys	Zinc	7440-66-6	0.006676	0.120007	1200	0.037094	371
Sub-Total			5.633	100	1000000	30.909437	309094
<b>Lead Frame Plating</b>							
Other Nonferrous Metals and Alloys	Tin	7440-31-5	0.7	100	1000000	3.841045	38410
Sub-Total			0.7	100	1000000	3.841045	38410
<b>Mold Compound</b>							
Other Inorganic Materials	Silica	7631-86-9	9.523304	88.699993	887000	52.256339	522563
Other Nonferrous Metals and Alloys	Metal Hydroxide	Trade Secret	0.322096	3	30000	1.767407	17674
Other Plastics and Rubber	Carbon Black	1333-86-4	0.03221	0.300004	3000	0.176743	1767
Thermoplastics	Epoxy	85954-11-6	0.858923	8.000003	80000	4.713088	47131
Sub-Total			10.736533	100	1000000	58.913578	589136
<b>Semiconductor Device</b>							
Ceramics / Glass	Doped Silicon	7440-21-3	0.863208	100	1000000	4.736601	47366
Sub-Total			0.863208	100	1000000	4.736601	47366
<b>Total</b>			18.224208			100	1000000

Important Note

The ppm calculations are at the homogeneous material level and are maximum concentration values. The ppm displayed represents the homogeneous material with the highest ppm for that substance. The amount (mg) calculations represent the maximum total amount of each substance within the component. The ppm calculations are at the component level and are average concentration values. The amount (mg) calculations represent the average total amount of each substance within the component. See Glossary of Terms for more details.

Important Part Information

There is a remote possibility the Customer Part Number (CPN) your company uses could reference more than one TI part number. This is due to two or more users (EMSI or subcontractors) using the same CPN for different TI part numbers. If this occurs, please check your Customer Part Number and cross reference it with the TI part number seen on this page.

Product Content Methodology

For an explanation of the methods used to determine material weights, See Product Content Methodology

Material Declaration Certificate for Semiconductor IC Packaged Products

TI certifies that the material content information provided by TI is representative and accurate to the best of their knowledge based on material information provided by its suppliers and their combination into finished IC packaged products. TI semiconductor products designated to be "Pb-free", "Green" or "RoHS Exempt" fully meets the latest EU RoHS Directive requirements along with other legislation as seen in the former JIG-101 list that has been transferred to the IEC 62474 database.

Important Information/Disclaimer

TI bases its material content information on information provided by third-party suppliers and has taken, and continues to take, reasonably diligent steps to provide any required or available information. TI may not have conducted destructive testing or chemical analysis on incoming materials and chemicals. TI and TI suppliers may consider certain information to be proprietary, and thus certain information may not be available for release by TI. The material content information is provided by TI "as is."

Signature: [\(click here for a fuller statement with a signed certificate\)](#)

Name/Title: Hubie Payne, Vice President, Worldwide SC Quality  
 For further environmental statements, please go to [www.ti.com/ecoinfo](http://www.ti.com/ecoinfo)  
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RoHS: Means TI semiconductor products that are compliant with the current RoHS requirement that the maximum concentration values of the ten substances listed in RoHS Annex II do not exceed 0.1 % by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI semiconductor products labeled as "RoHS Compliant" are suitable for use in specified lead-free processes. TI may also reference these types of semiconductor products as "Pb-Free." These TI semiconductor products are also fully compliant with GADSL and the IEC 62474 database for electronic requirements.

RoHS Exempt: Means TI semiconductor products that contain lead (Pb) above the RoHS Annex II threshold, but that fall within one of the specific RoHS exemptions noted above or documented in <http://www.ti.com/lit/pdf/szzq088>

Green: Means the content of Chlorine (Cl) and Bromine (Br)-based flame retardants meet JS709B low halogen requirements of <=1 000ppm threshold; Antimony trioxide (Sb2O3) contained in halogen based flame retardant materials meets the <=1 000ppm threshold requirement; and Beryllium Oxide (BeO) is <=1000ppm.